

CHANGE NOTIFICATION



Linear Technology Corporation
1630 McCarthy Blvd., Milpitas, CA 95035-7417
(408) 432-1900

July 30, 2014

Dear Sir/Madam:

PCN# 073014

Subject: Notification of Additional Assembly Location, ASE Korea for LTM4616

Please be advised that Linear Technology Corporation has successfully qualified ASE Korea as an assembly site for the subject packages. It was desirable to qualify ASE Korea to serve as an alternate source since it is located in a different geographic area than our existing assembly location in Penang, Malaysia. ASE Korea is ISO9002, QS9000, ISO14001, TS16949, OHSAS 18001 and QC80000 certified. A summary of ASE Korea's product mix and LTC's qualification results are shown on the attached pages. The facility passed a site audit by LTC's supplier quality organization. LTC product assembled in ASE Korea can be identified by the country of origin marked on the device as "KR". The product photo showing the ASE Korea marking is attached. The Approximate datecode of the first units assembled by ASE Korea, and the list of affected part numbers is presented below in the table.

Part Number	Part Marking	Package Type	Datecode (Approx.)
LTM4616EV#PBF	LTM4616V	LGA	1414
LTM4616IV#PBF	LTM4616V	LGA	

In addition, a minor change to the internal package construction was made on this device in order to facilitate the use of one attach material for both die and components. The die attach material is changed from epoxy to solder, which is already used for attaching components in the same μ Module device package. In order to use the solder die attach, the die attach paddle (DAP) has been modified by splitting the DAP into multiple pads for dice U1 and U2. Linear has been shipping several μ Module devices using solder for die attach and component attach.

Parts incorporating the new substrate design have been fully characterized and tested for package level reliability. The change was qualified by performing extensive characterization over the full operating voltage and temperature ranges and MSL3 preconditioning. Devices from the same μ Module device product family have been subjected to 1000 cycles of temperature cycles and thermal shock. Linear Technology performs reliability testing on production lots in accordance with our Quick Reaction Reliability (QR2) Monitor Program. This monitor program is designed to provide fast feedback for possible reliability problems associated with package assembly. Please provide an expeditious approval to this PCN, so that LTC can build subject packages at ASE.

Should you have any concerns, please contact me before September 30, 2014, at which time we will consider this change to be approved. If you have any questions or concerns, please feel free to contact me at (408) 432-1900 ext. 2077 or by e-mail at JASON.HU@LINEAR.COM.

Sincerely,

Jason Hu
Quality Assurance Engineer

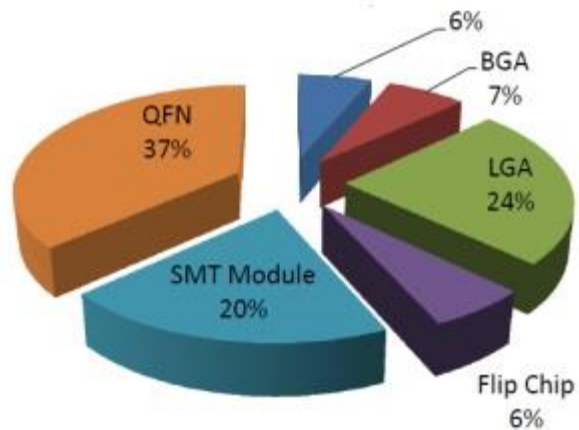
ASE Korea Capacity Summary

ASE Korea
76, Saneopdanji-gil, Paju-si,
Gyeonggi-do, Korea
Tel: 82-31-9400-114, 82-31-9400-539
Head counts: 2,791

Package Portfolio - Breakdown

- Analog Power for Automotive
- RF for digital/consumer
- MEMS for safety
- Array Packages

2013 Production Mix by Package



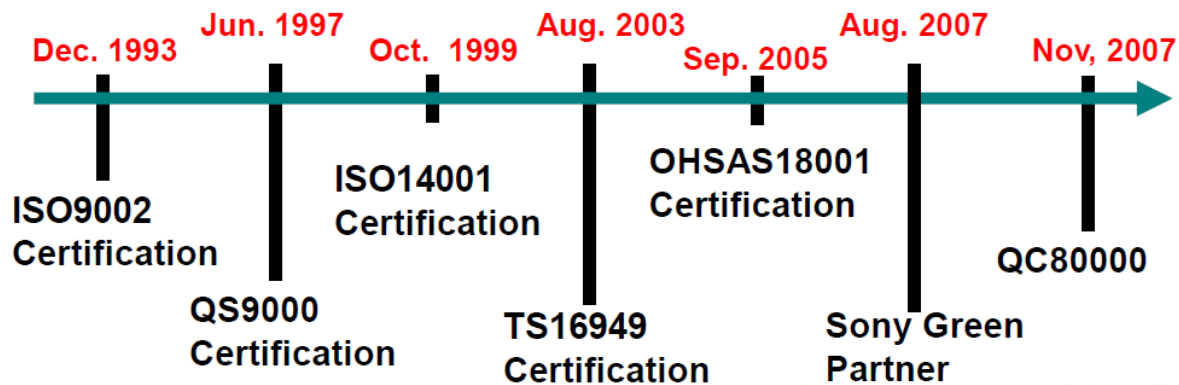
Quality System Certification



- ISO9002 certified by SGS-Yarsely in December 1993.
- QS9000 certified by LRQA in June 1997
- ISO14001 certified by LRQA in October 1999
- TS16949 certified by LRQA in August 2003
- OHSAS18001 certified by KFQ in September 2005
- Sony Green Partner certified by Sony in August 2007
- QC80000 certified by SGS in November 2007

*Surveillance Audit : Every 6 Months

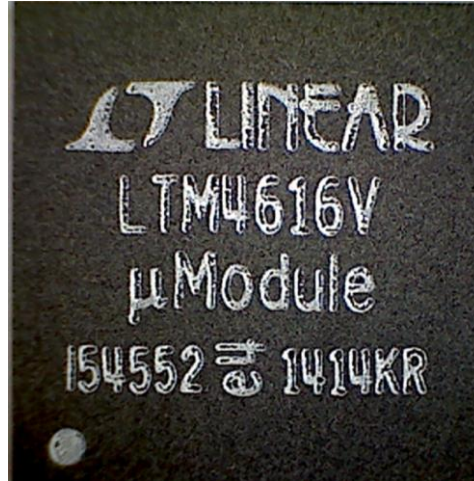
--- Assessment History-----



Confidential Statement

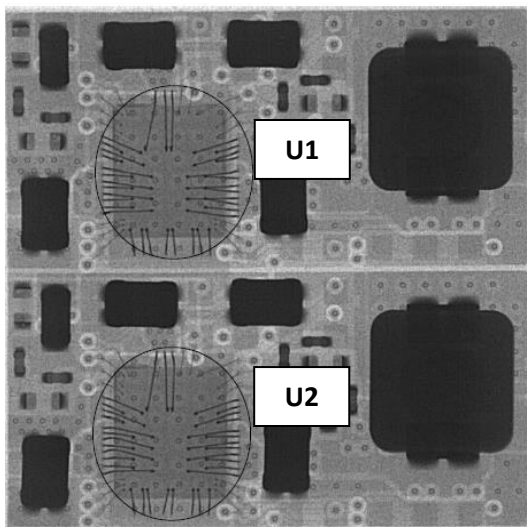
This change notice is for Linear Technology's Customers only.
Distribution or notification to third parties is prohibited.

Country of Origin on Top Mark



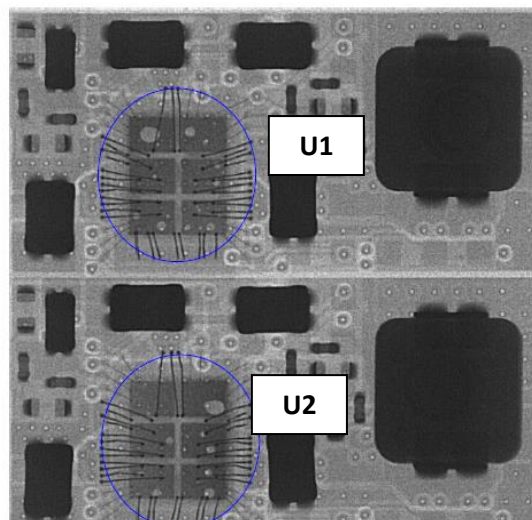
Before

LTM4616-EPOXY DIE ATTACH



After

LTM4616-SOLDER DIE ATTACH



Confidential Statement

This change notice is for Linear Technology's Customers only.
Distribution or notification to third parties is prohibited.

PACKAGE RELIABILITY DATA LTM4616 / LTM4619 / LTM8023 / LTM8032 ASE ASSEMBLY SITE QUALIFICATION 7/8/2014					
• J-STD-020 MSL 3 PRECONDITIONING: 192h +30°C/60%R.H. SOAK, 3x REFLOW AT +245°C PEAK					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES
LTM4616	231	1414	1414		0
LTM4619	231	1411	1411		0
LTM8023	385	1411	1411		0
LTM8032	385	1411	1411		0
	1,232				0
• TEMP CYCLE FROM -55°C to +125°C ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM4616	77	1414	1414	38.50	0
LTM4619	77	1411	1411	38.50	0
LTM8023	77	1411	1411	38.50	0
LTM8032	77	1411	1411	38.50	0
	308			154.00	0
• TEMP CYCLE FROM -65°C to +150°C ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8023	77	1411	1411	38.50	0
LTM8032	77	1411	1411	77.00	0
	154			115.50	0
• THERMAL SHOCK FROM -55°C to +125°C ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM4616	74	1414	1414	37.00	0
LTM4619	77	1411	1411	77.00	0
LTM8023	77	1411	1411	77.00	0
LTM8032	77	1411	1411	38.50	0
	305			229.50	0
• THERMAL SHOCK FROM -65°C to +150°C ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
LTM8023	77	1411	1411	77.00	0
LTM8032	77	1411	1411	77.00	0
	154			154.00	0
• HIGH TEMPERATURE STORAGE +150°C					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +150°C	NUMBER OF FAILURES
LTM4616	77	1414	1414	38.50	0
LTM4619	77	1411	1411	77.00	0
LTM8023	77	1411	1411	77.00	0
LTM8032	77	1411	1411	77.00	0
	308			269.50	0
• UNBIASED HIGHLY ACCELERATED STRESS TEST +130°C/85% R.H. ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +130°C	NUMBER OF FAILURES
LTM4616	77	1411	1411	3.70	0
	77			3.70	0
• UNBIASED TEMPERATURE/HUMIDITY STORAGE TEST +85°C/85% R.H. ⁽¹⁾					
DEVICE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C	NUMBER OF FAILURES
LTM8023	77	1411	1411	38.50	0
LTM8032	77	1411	1411	38.50	0
	154			77.00	0

(1) Environmental stress are preceded by J-STD-020 Level 3 Preconditioning: 192h 30°C/60% R.H. soak, followed by 3x Reflow at 245°C.